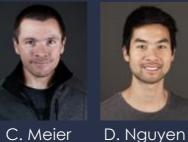


F. Droz

J. Holzer









A. Ummel S. Humbert

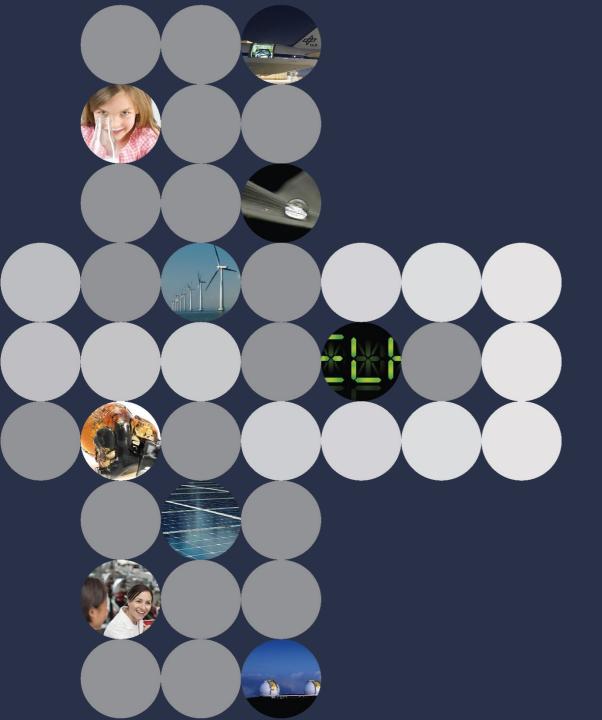
New Space Flash LiDAR: **Development Trade-Offs and Applications**

Christophe Pache, Group Leader, CSEM christophe.pache@csem.ch



13-14 September 2022 Noordwijk, The Netherlands EPIC Meeting on Photonics at the Final Frontier at European Space Agency (ESA)





CSEM

Facing **the** challenges of **our** time

2)

Our mission



3

Development and transfer of world-class (micro-)technologies to the industrial sector in order to reinforce its competitive advantage.

- Cooperation agreements with established companies
- Encouraging the creation of start-ups

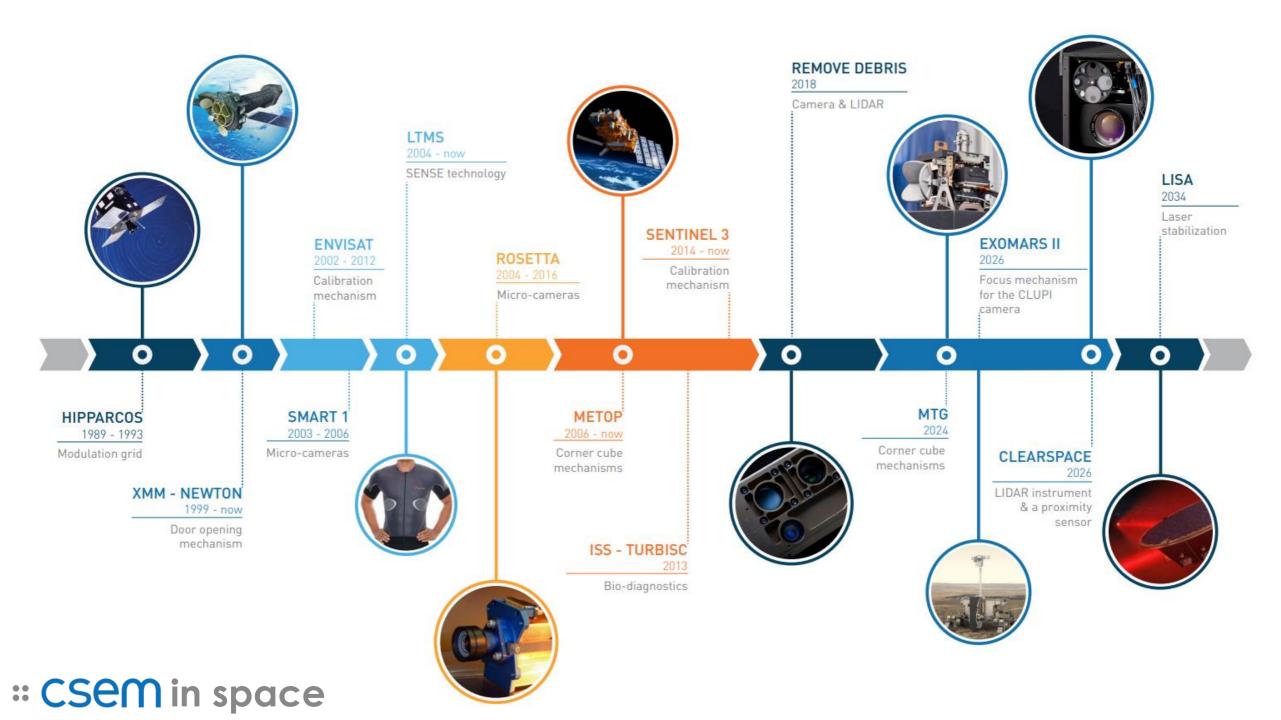


CSEM at a glance



(4)

" CSem







6

"CSem

Expertise

- System design & integration
- Miniaturisation

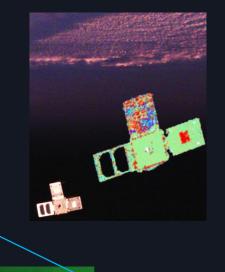
1. Flash imaging LiDAR

- Snapshot acquisition (< 20 ms)</p>
- > High spatial resolution
- Adaptive field-of-view



Applications

- Space: 3D pose estimation
- Bathymetry
- All-weather navigation
- Geodesy
- Environment perception

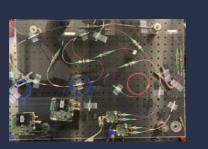


pation ception

- Surface metrology additive manufacturing
- Gas sensing

2. FMCW LiDAR

- ➤ Invisible
- Coherent
- > High axial precision (< 50 μm)</p>



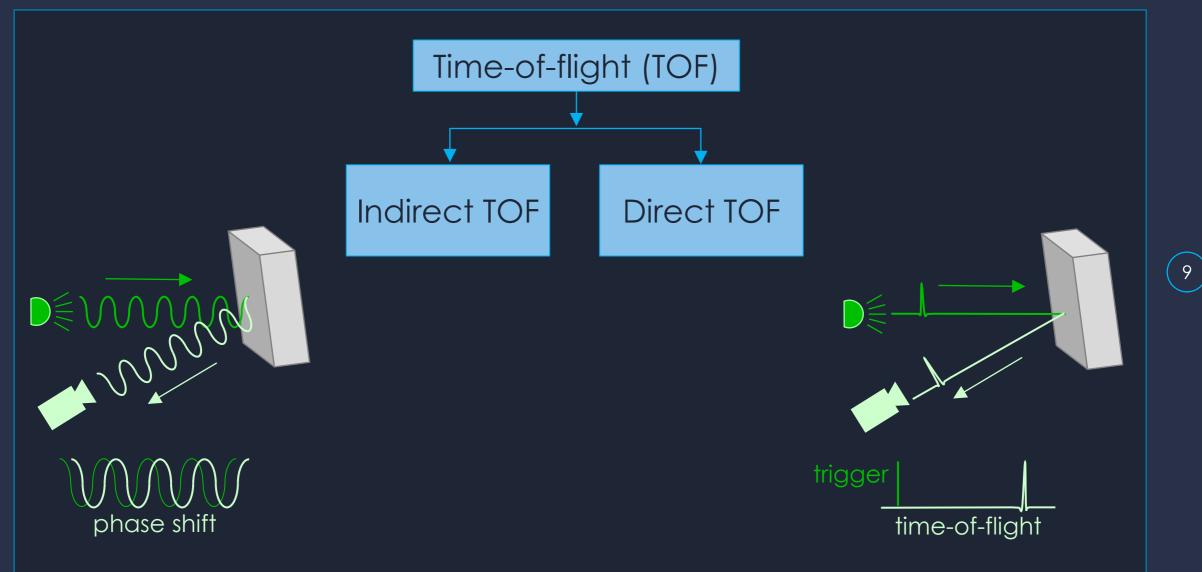


Flash imaging LiDAR

CSEM's developments & positioning

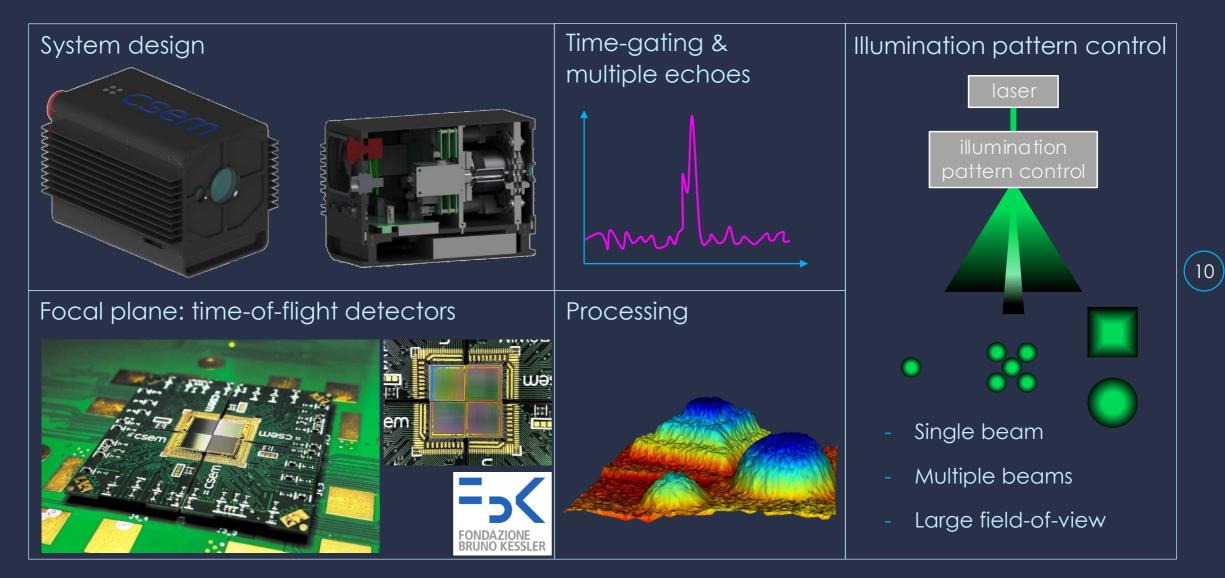
æ VIM S AIR . "CSem

Imaging TOF technologies





Hybrid flash imaging LiDAR



" csem

Current LIDAR specifications

Specifications	AIRSWIM	RemoveDebris	
Application	Bathymetry	Space (rendezvous)	
Architecture	d-TOF	i-TOF	
Laser	Pulsed, Class 4, λ = 532 nm	Laser diode, Class 4, λ = 808 nm, cw mod.	
Sensor resolution	128 x 128 <u>2023</u> : 256 x 256 or 512 x 512	120 x 160	
Precision	< 5 cm at 100 m in air	< 10 cm at 60 m	
FOV [°]	5 - 20	20	
Size [cm ³]	20 x 17 x 19	10 x 10 x 15	
Weight [kg]	6.5	< 2	
Power consumption [W]	< 55	15	
Frame rate [Hz]	> 4 (target: 10)	20	



AIRSWIM





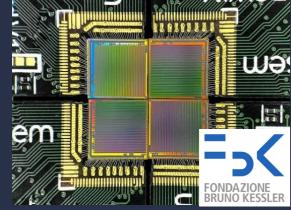
" CSem



Space Applications

High-end development path

- Landing application
- Direct-TOF SPC architecture, 2018: TRL4 delivered to ESA

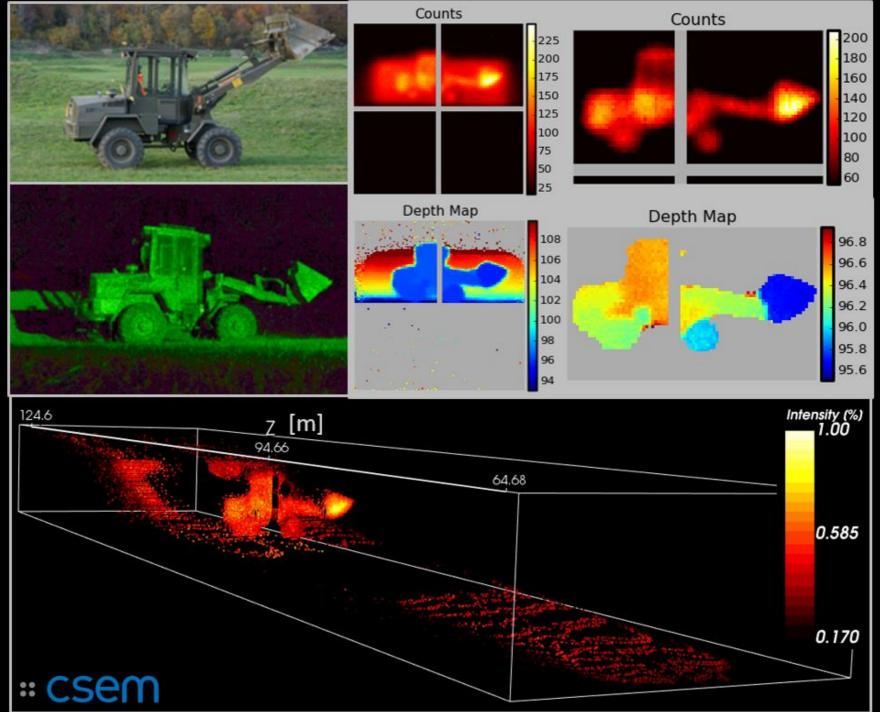


MILA64 detector









Debris removal missions – New Space

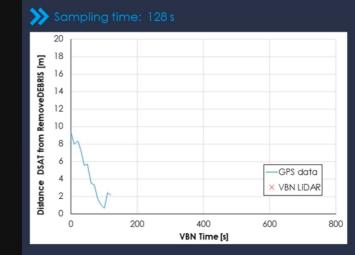


RemoveDEBRIS

- Launch with SpaceX in April 2018
- NET and VBN in-orbit experiments
- Mission end April 2019



VBN experiment data



• ADRIOS

- Launch: 2025
- Further miniaturisation
- Embedded processing, i.e. system-on-chip # CSEM

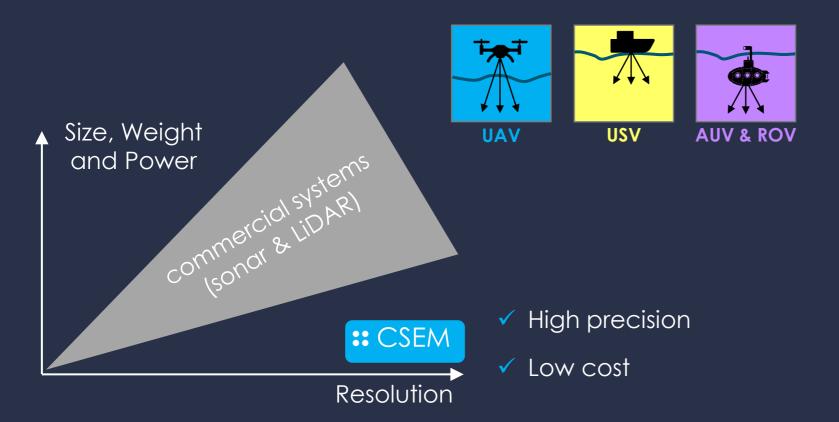
Confirmed potential for **future** commercialisation (in-orbit maneuvers)

Bathymetric Applications

UNDERWATER 3D IMAGING

Multi-platform flash LiDAR

CSEM key differentiators and positioning



Synergies with **Space**:

- \succ Remote operation \rightarrow autonomy
- > Low power
- > Miniaturisation constraints



Shallow water 3D mapping



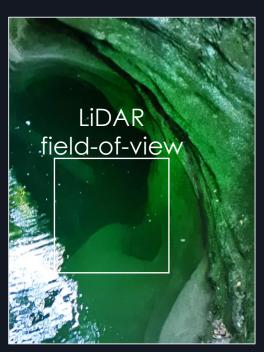
Infrastructure monitoring



Objects detection

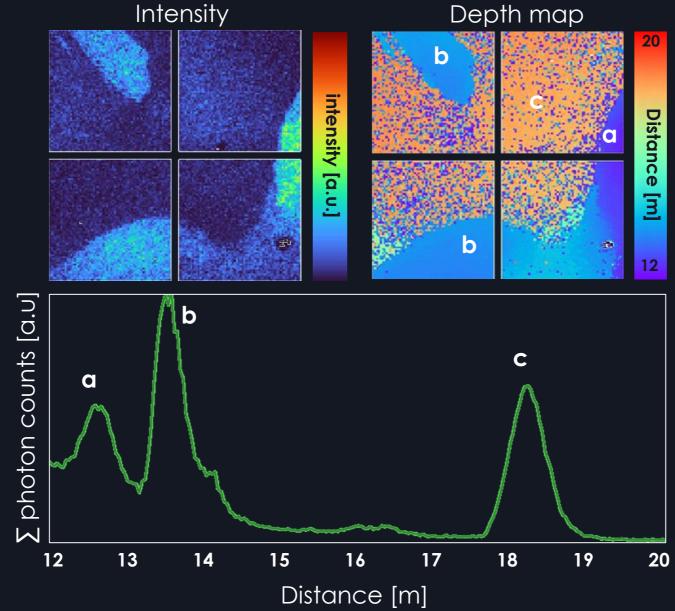
Munkholmen island, Trondheim, Norway

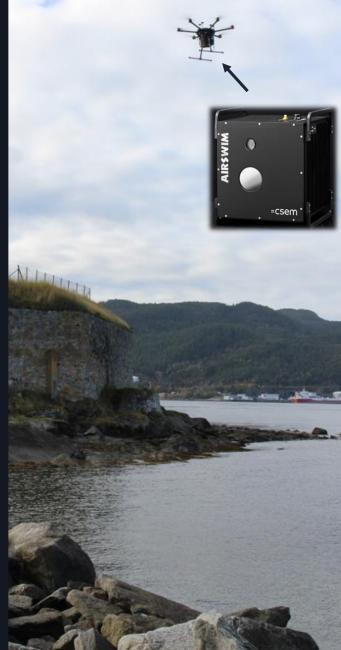
Airbone underwater imaging



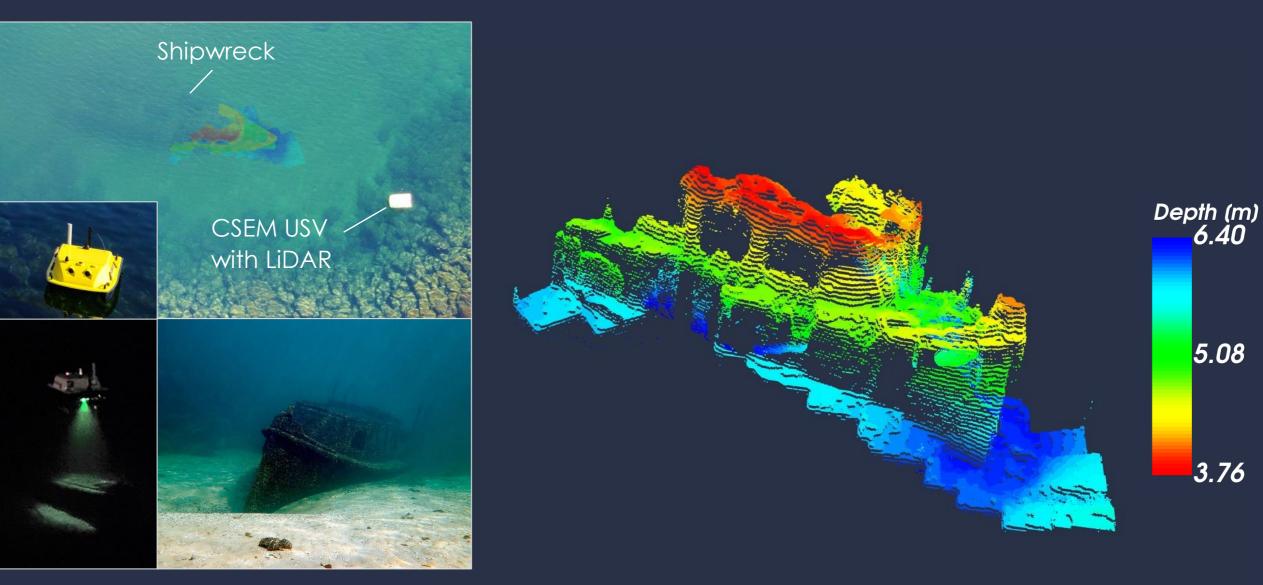
Areuse river, Neuchâtel, Switzerland

CSem





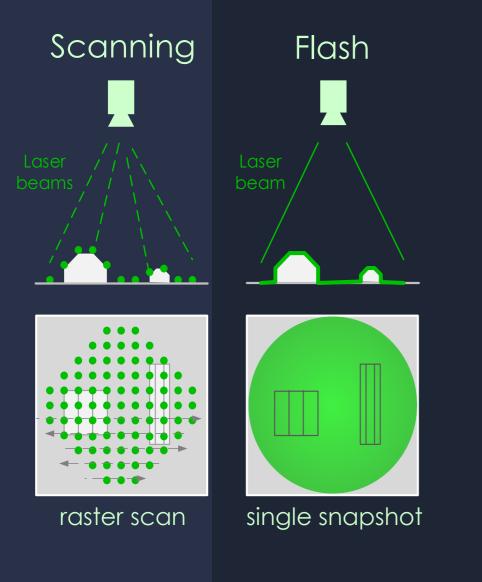
Demonstration from unmanned surface vehicle (USV)



" CSem

Trade-offs & challenges

Architecture comparison



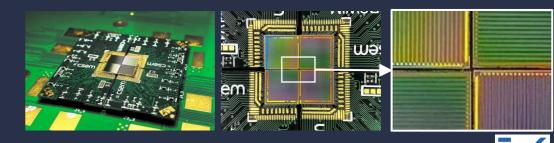
" CSem

- **Simplicity & reliabiliy:** better integration & product lifetime
- High resolution: diffraction-limited, no influence of possible scanning mechanism precision
- Snapshot acquisition & high frame rate: robust against motion blur and vibrations
- Limited field-of-view and/or range
- Sensitivity to sunlight \rightarrow optics & electronics mitigations

Well-suited for certain applications

Need for adaptation of **mission requirements**

Multidisciplinary system design



> Optical design > system integration time-of-flight detectors **FONDAZIONE** BRUNO KESSLER 23 heat & vibration management > fast electronics (active gating) massive data flow and " CSem embedded processing

Data flow & processing

- Targeted performances
 - Frame rate: 10 Hz

Embedded

• Exposure time: < 20 ms

real-time processing

128

128

2048

500 Mbits

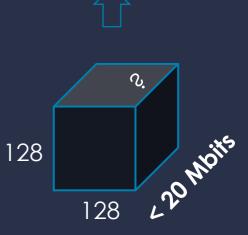
massive data rate: > 625 GB/s

compression factor: 25

real-time

- Parallel read-out
- Fast memory access

Use state-of-the-art system-on-chip



« csem

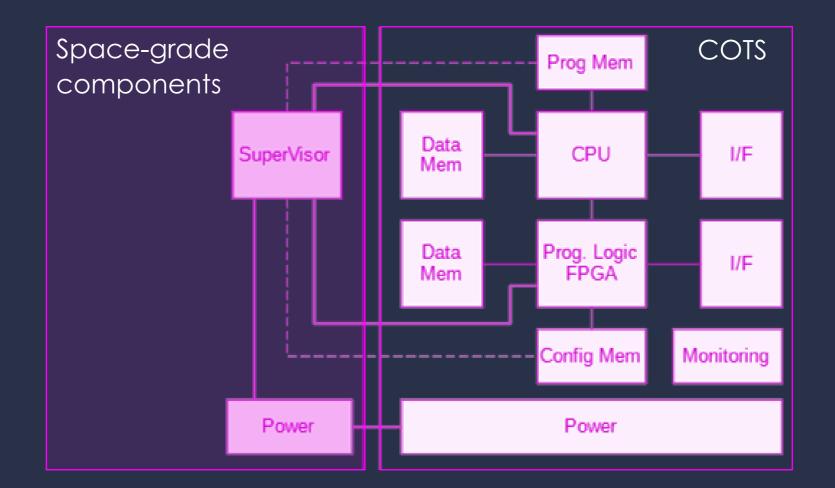
New Space electronics design – reliability risk assessment

Hardware	SW/FW mitigations	Advantages	Drawbacks	Redundancy
Space- grade	Embedded redundancyMemory protection	 Qualified technology 	 Expensive Lack of performances 	D Flip-Flop 2 Flip-Flop 3
COTS	 Additional redundancy Memory & configuration protection (scrubbing) Power control Supervision 	 Low cost Recent technology: high perf. & ease of integration 	 Higher risk on reliability 	In Function 2 Function 3



System-level mitigations at hardware level

- Enhanced reliability and performance at reasonable cost
- Mitigate risks of propagating damages to spaceraft and system itself





Opportunities

Thank you for your attention!

Christophe Pache Group Leader, Sensing & Control christophe.pache@csem.ch T +41 32 720 59 02 M +41 79 794 29 16



28

www.csem.ch

